



# BUK4D110-20P

20 V, P-channel Trench MOSFET

7 July 2020

Product data sheet

## 1. General description

P-channel enhancement mode Field-Effect Transistor (FET) in a medium power DFN2020MD-6 (SOT1220) Surface-Mounted Device (SMD) plastic package using Trench MOSFET technology.

## 2. Features and benefits

- Extended temperature range  $T_j = 175\text{ °C}$
- Trench MOSFET technology
- Very fast switching
- Side wettable flanks for optical solder inspection
- ElectroStatic Discharge (ESD) protection > 1 kV HBM (class H1C)
- AEC-Q101 qualified

## 3. Applications

- DC to DC conversion
- High-speed line driver
- High-side load switch
- Switching circuits

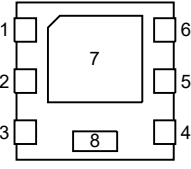
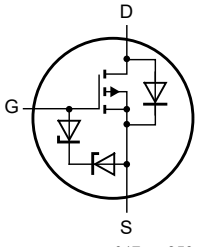
## 4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{DS}$	drain-source voltage	$T_j = 25\text{ °C}$	-	-	-20	V
$V_{GS}$	gate-source voltage		-12	-	12	V
$I_D$	drain current	$V_{GS} = -4.5\text{ V}; T_{sp} = 25\text{ °C}$	-	-	-6.7	A
$P_{tot}$	total power dissipation	$T_{sp} = 25\text{ °C}$	-	-	7.5	W
<b>Static characteristics</b>						
$R_{DSon}$	drain-source on-state resistance	$V_{GS} = -4.5\text{ V}; I_D = -3.4\text{ A}; T_j = 25\text{ °C}$	-	88	110	mΩ

## 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	D	drain	 <p>Transparent top view DFN2020MD-6 (SOT1220)</p>	 <p>017aaa259</p>
2	D	drain		
3	G	gate		
4	S	source		
5	D	drain		
6	D	drain		
7	D	drain		
8	S	source		

## 6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BUK4D110-20P	DFN2020MD-6	plastic, leadless thermal enhanced ultra thin small outline package with side-wettable flanks (SWF); 6 terminals; 0.65 mm pitch; 2 mm x 2 mm x 0.65 mm body	SOT1220

## 7. Marking

Table 4. Marking codes

Type number	Marking code
BUK4D110-20P	6N

## 8. Limiting values

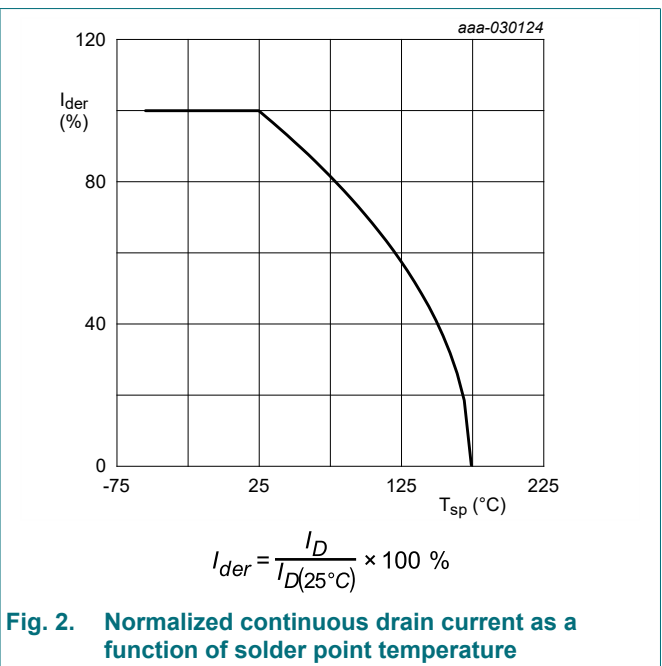
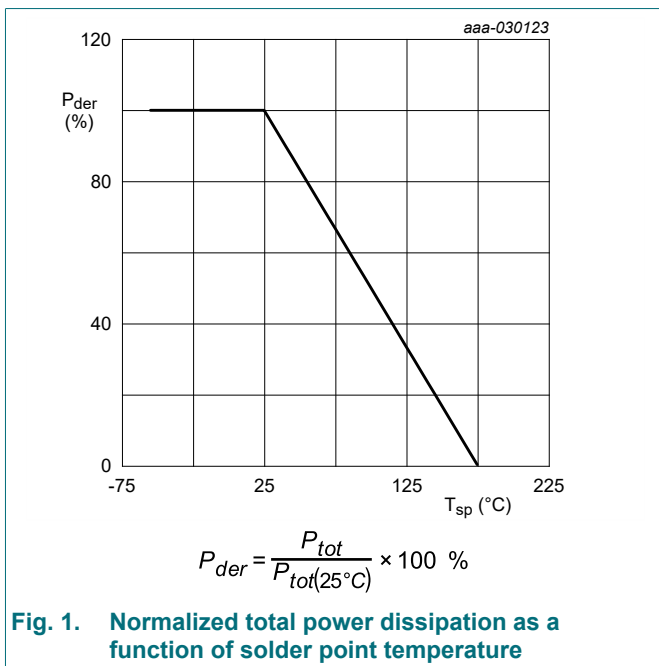
**Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>DS</sub>	drain-source voltage	T <sub>j</sub> = 25 °C	-	-20	V
V <sub>GS</sub>	gate-source voltage		-12	12	V
I <sub>D</sub>	drain current	V <sub>GS</sub> = -4.5 V; T <sub>sp</sub> = 25 °C	-	-6.7	A
		V <sub>GS</sub> = -4.5 V; T <sub>sp</sub> = 100 °C	-	-4.2	A
		V <sub>GS</sub> = -4.5 V; T <sub>amb</sub> = 25 °C	[1]	-3.4	A
I <sub>DM</sub>	peak drain current	T <sub>sp</sub> = 25 °C; single pulse; t <sub>p</sub> ≤ 10 μs	-	-27	A
P <sub>tot</sub>	total power dissipation	T <sub>sp</sub> = 25 °C	-	7.5	W
		T <sub>amb</sub> = 25 °C	[1]	2	W
T <sub>j</sub>	junction temperature		-55	175	°C
T <sub>amb</sub>	ambient temperature		-55	175	°C
T <sub>stg</sub>	storage temperature		-65	175	°C
<b>Source-drain diode</b>					
I <sub>S</sub>	source current	T <sub>sp</sub> = 25 °C	-	-6.7	A
		T <sub>amb</sub> = 25 °C	[1]	-1.9	A
I <sub>SM</sub>	peak source current	single pulse; t <sub>p</sub> ≤ 10 μs; T <sub>sp</sub> = 25 °C	-	-27	A
<b>ESD maximum rating</b>					
V <sub>ESD</sub>	electrostatic discharge voltage	HBM	[2]	1000	V
<b>Avalanche ruggedness</b>					
E <sub>DS(AL)S</sub>	non-repetitive drain-source avalanche energy	T <sub>j(init)</sub> = 25 °C; I <sub>D</sub> = -0.5 A; DUT in avalanche (unclamped)	-	5	mJ

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and mounting pad for drain 6 cm<sup>2</sup>.

[2] Measured between all pins.



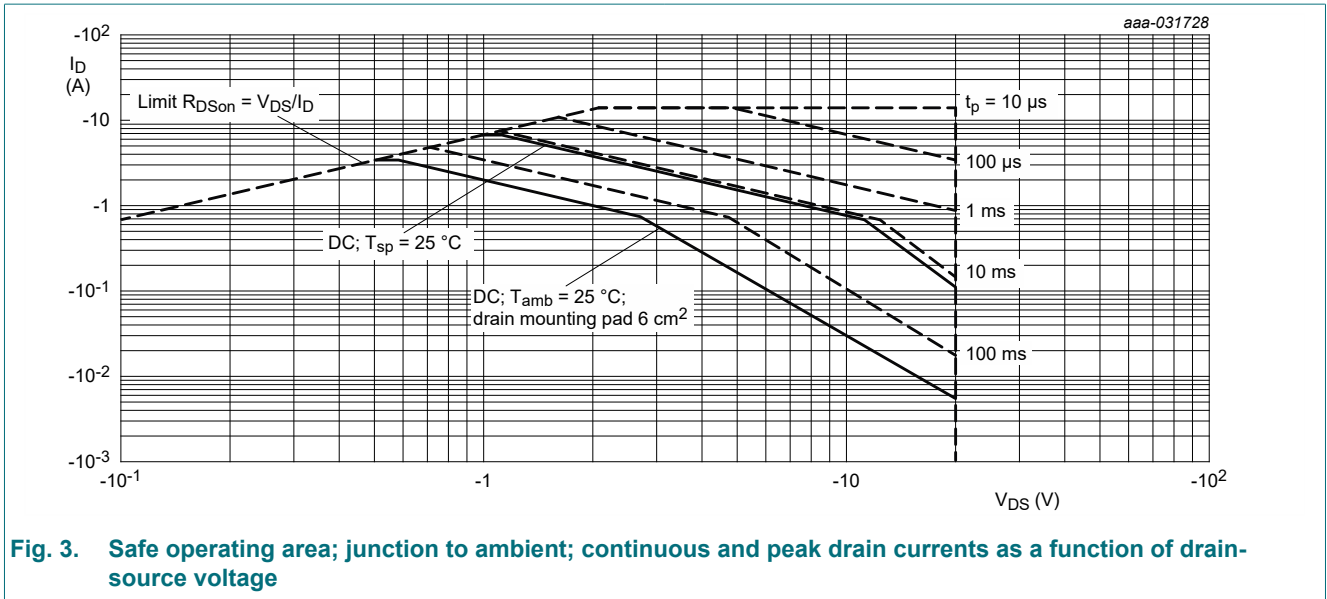


Fig. 3. Safe operating area; junction to ambient; continuous and peak drain currents as a function of drain-source voltage

### 9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]	-	66	76	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point			-	15	20	K/W

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and mounting pad for drain 6 cm<sup>2</sup>.

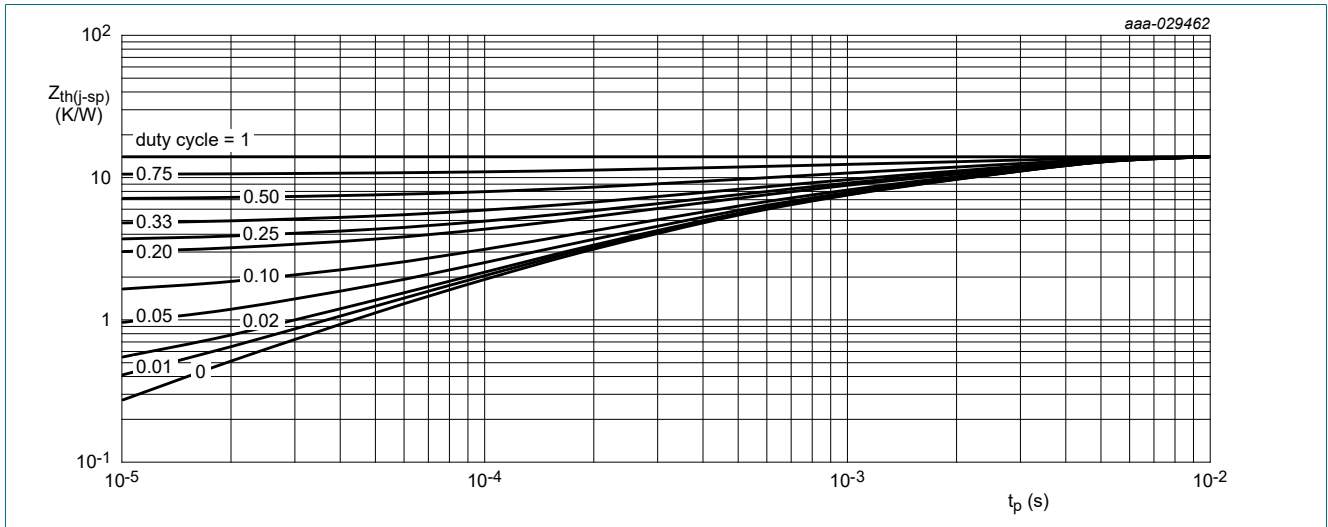


Fig. 4. Transient thermal impedance from junction to solder point as a function of pulse duration; typical values

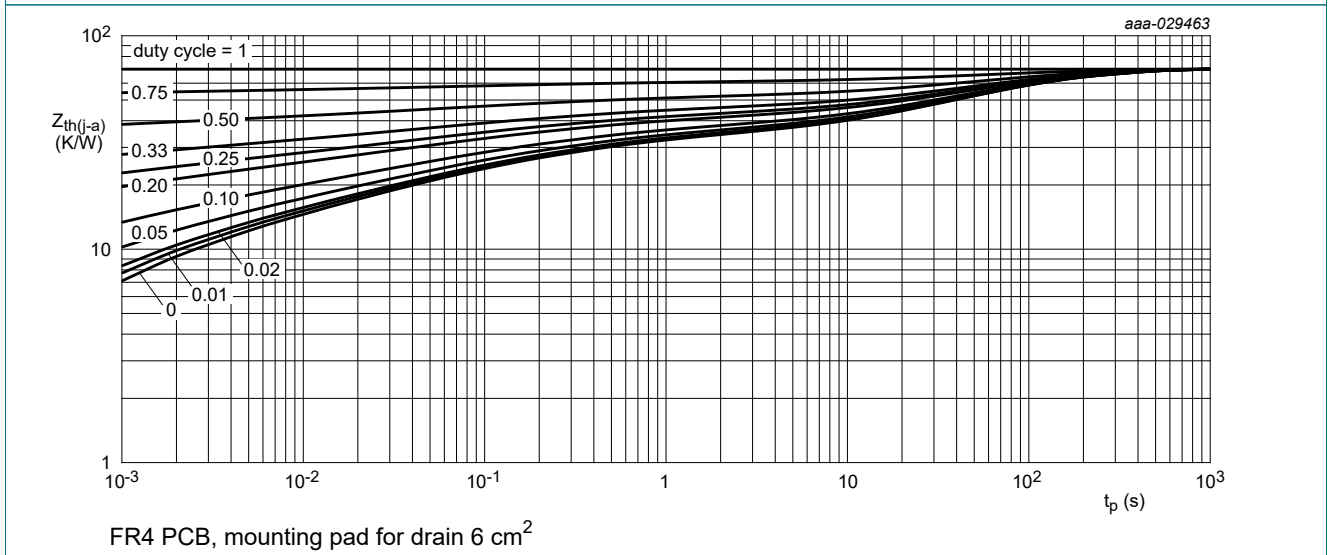


Fig. 5. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

## 10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static characteristics</b>						
$V_{(BR)DSS}$	drain-source breakdown voltage	$I_D = -250 \mu A$ ; $V_{GS} = 0 V$ ; $T_j = 25 \text{ }^\circ C$	-20	-	-	V
$V_{GSth}$	gate-source threshold voltage	$I_D = -250 \mu A$ ; $V_{DS} = V_{GS}$ ; $T_j = 25 \text{ }^\circ C$	-0.6	-0.95	-1.3	V
$I_{DSS}$	drain leakage current	$V_{DS} = -20 V$ ; $V_{GS} = 0 V$ ; $T_j = 25 \text{ }^\circ C$	-	-	-1	$\mu A$
		$V_{DS} = -20 V$ ; $V_{GS} = 0 V$ ; $T_j = 125 \text{ }^\circ C$	-	-	-20	$\mu A$
$I_{GSS}$	gate leakage current	$V_{GS} = -12 V$ ; $V_{DS} = 0 V$ ; $T_j = 25 \text{ }^\circ C$	-	-	-10	$\mu A$
		$V_{GS} = 12 V$ ; $V_{DS} = 0 V$ ; $T_j = 25 \text{ }^\circ C$	-	-	10	$\mu A$
		$V_{GS} = -4.5 V$ ; $V_{DS} = 0 V$ ; $T_j = 25 \text{ }^\circ C$	-	-	-2	$\mu A$
		$V_{GS} = 4.5 V$ ; $V_{DS} = 0 V$ ; $T_j = 25 \text{ }^\circ C$	-	-	2	$\mu A$
$R_{DSon}$	drain-source on-state resistance	$V_{GS} = -8 V$ ; $I_D = -3.4 A$ ; $T_j = 25 \text{ }^\circ C$	-	75	96	m $\Omega$
		$V_{GS} = -8 V$ ; $I_D = -3.4 A$ ; $T_j = 175 \text{ }^\circ C$	-	116	148	m $\Omega$
		$V_{GS} = -4.5 V$ ; $I_D = -3.4 A$ ; $T_j = 25 \text{ }^\circ C$	-	88	110	m $\Omega$
		$V_{GS} = -2.5 V$ ; $I_D = -1 A$ ; $T_j = 25 \text{ }^\circ C$	-	138	189	m $\Omega$
$g_{fs}$	forward transconductance	$V_{DS} = -10 V$ ; $I_D = -3.4 A$ ; $T_j = 25 \text{ }^\circ C$	-	6	-	S
$R_G$	gate resistance	$f = 1 \text{ MHz}$	-	36	-	$\Omega$
<b>Dynamic characteristics</b>						
$Q_{G(tot)}$	total gate charge	$V_{DS} = -10 V$ ; $I_D = -3.2 A$ ; $V_{GS} = -4.5 V$ ; $T_j = 25 \text{ }^\circ C$	-	3.6	5	nC
$Q_{GS}$	gate-source charge		-	0.8	-	nC
$Q_{GD}$	gate-drain charge		-	1.2	-	nC
$C_{iss}$	input capacitance	$V_{DS} = -10 V$ ; $f = 1 \text{ MHz}$ ; $V_{GS} = 0 V$ ; $T_j = 25 \text{ }^\circ C$	-	365	-	pF
$C_{oss}$	output capacitance		-	49	-	pF
$C_{rss}$	reverse transfer capacitance		-	39	-	pF
$t_{d(on)}$	turn-on delay time	$V_{DS} = -10 V$ ; $I_D = -3.2 A$ ; $V_{GS} = -4.5 V$ ; $R_{G(ext)} = 6 \Omega$ ; $T_j = 25 \text{ }^\circ C$	-	4	-	ns
$t_r$	rise time		-	7	-	ns
$t_{d(off)}$	turn-off delay time		-	9	-	ns
$t_f$	fall time		-	7	-	ns
<b>Source-drain diode</b>						
$V_{SD}$	source-drain voltage	$I_S = -2 A$ ; $V_{GS} = 0 V$ ; $T_j = 25 \text{ }^\circ C$	-	-0.9	-1.2	V
$t_{rr}$	reverse recovery time	$I_S = -2 A$ ; $dI_S/dt = 100 A/\mu s$ ; $V_{GS} = 0 V$ ; $V_{DS} = -10 V$ ; $T_j = 25 \text{ }^\circ C$	-	9	-	ns
$Q_r$	recovered charge		-	2	-	nC

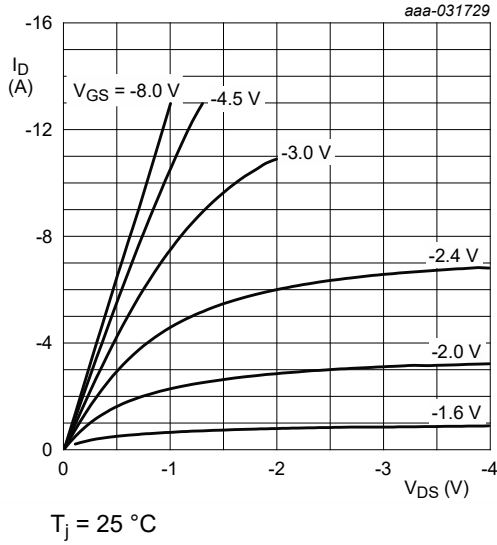


Fig. 6. Output characteristics: drain current as a function of drain-source voltage; typical values

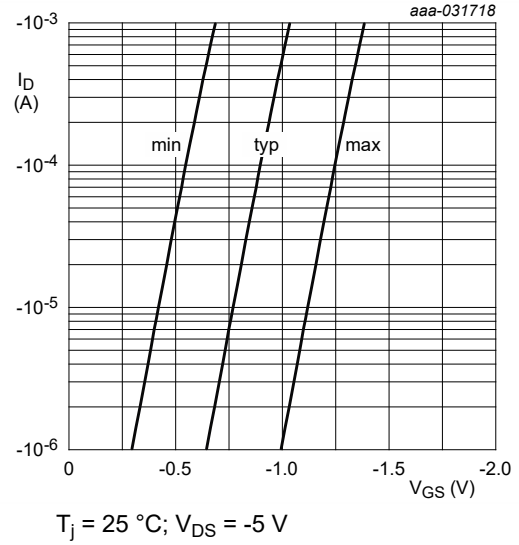


Fig. 7. Sub-threshold drain current as a function of gate-source voltage

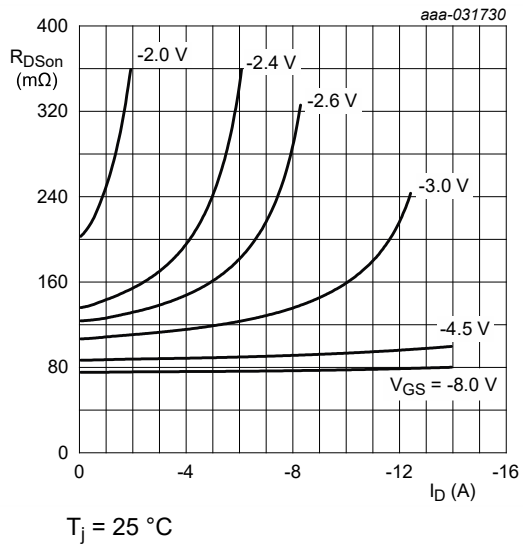


Fig. 8. Drain-source on-state resistance as a function of drain current; typical values

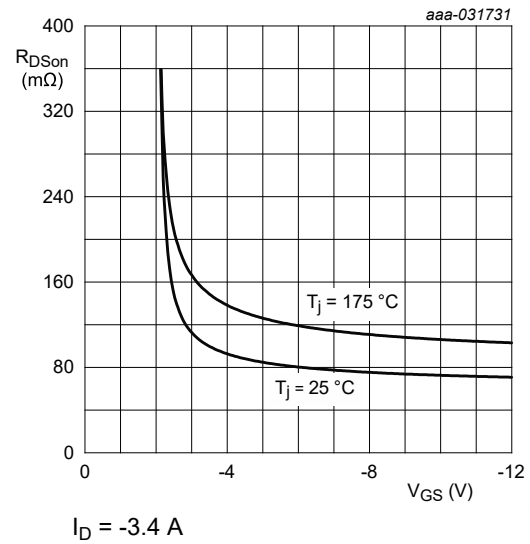


Fig. 9. Drain-source on-state resistance as a function of gate-source voltage; typical values

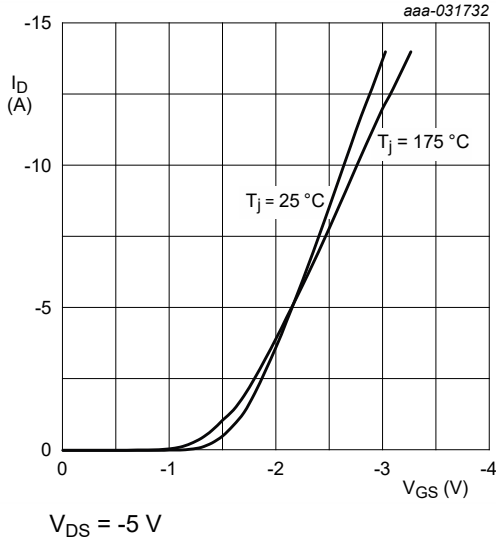


Fig. 10. Transfer characteristics: drain current as a function of gate-source voltage; typical values

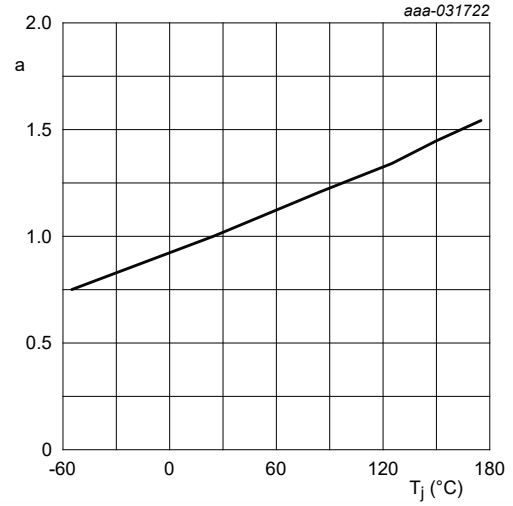


Fig. 11. Normalized drain-source on-state resistance as a function of junction temperature; typical values

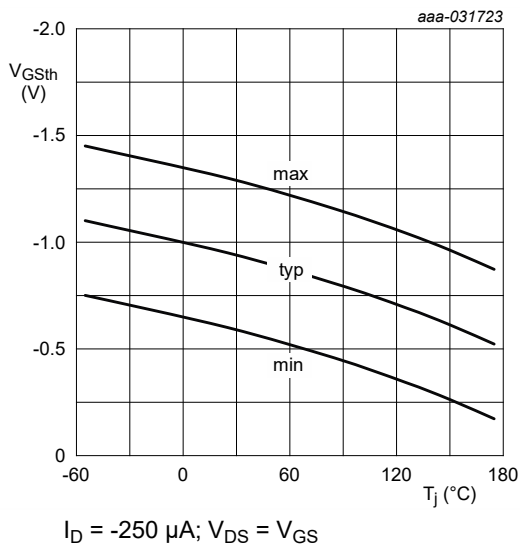


Fig. 12. Gate-source threshold voltage as a function of junction temperature

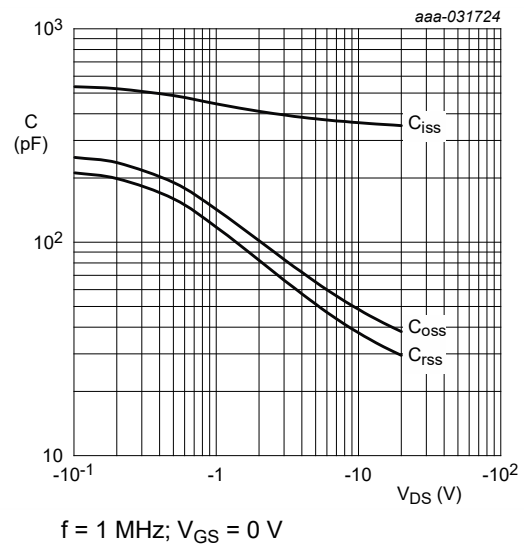
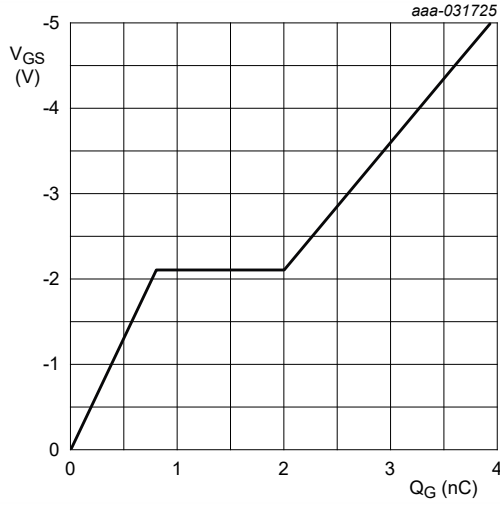


Fig. 13. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values





$I_D = -3.2$  A;  $V_{DS} = -10$  V;  $T_j = 25$  °C

Fig. 14. Gate-source voltage as a function of gate charge; typical values

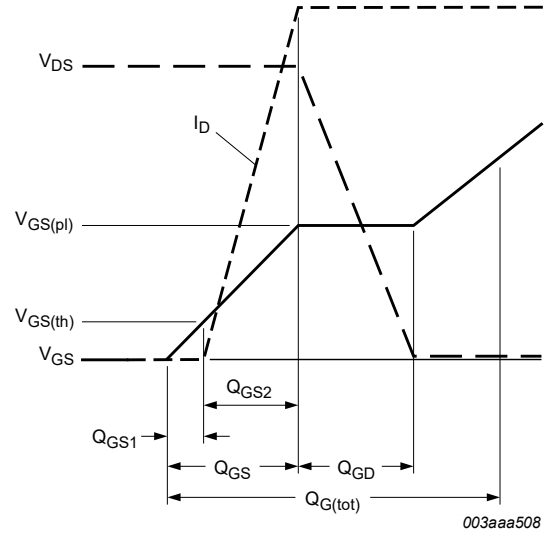
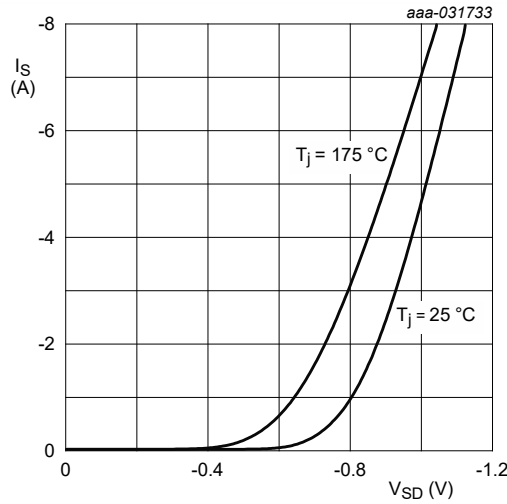


Fig. 15. Gate charge waveform definitions



$V_{GS} = 0$  V

Fig. 16. Source current as a function of source-drain voltage; typical values

## 11. Test information

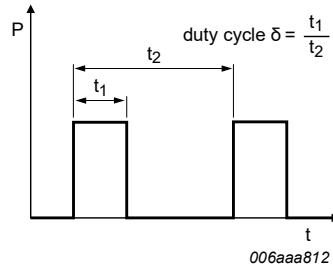


Fig. 17. Duty cycle definition

### Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - *Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

## 12. Package outline

DFN2020MD-6: plastic thermal enhanced ultra thin small outline package; no leads;  
6 terminals; body 2 x 2 x 0.65 mm

SOT1220

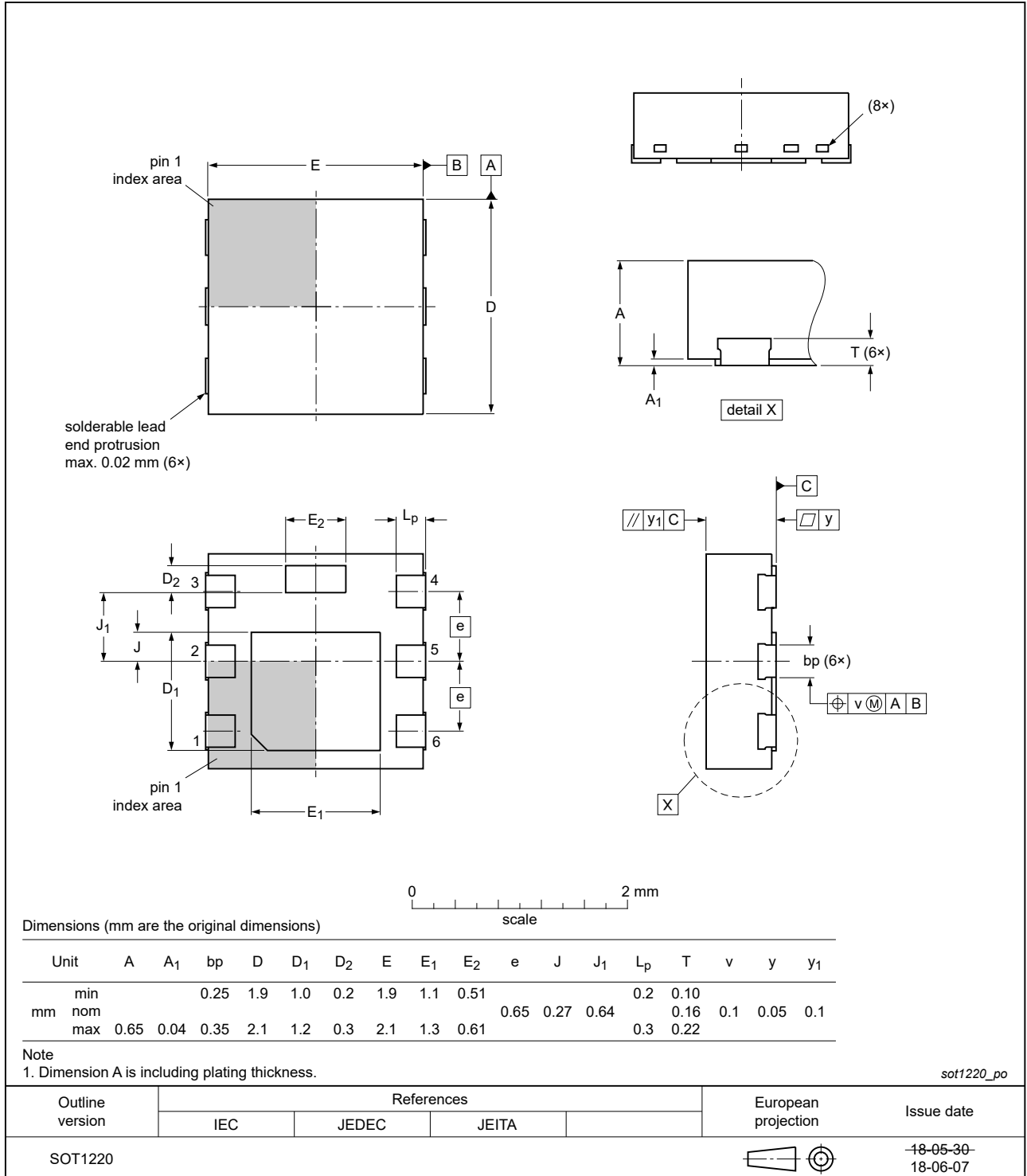
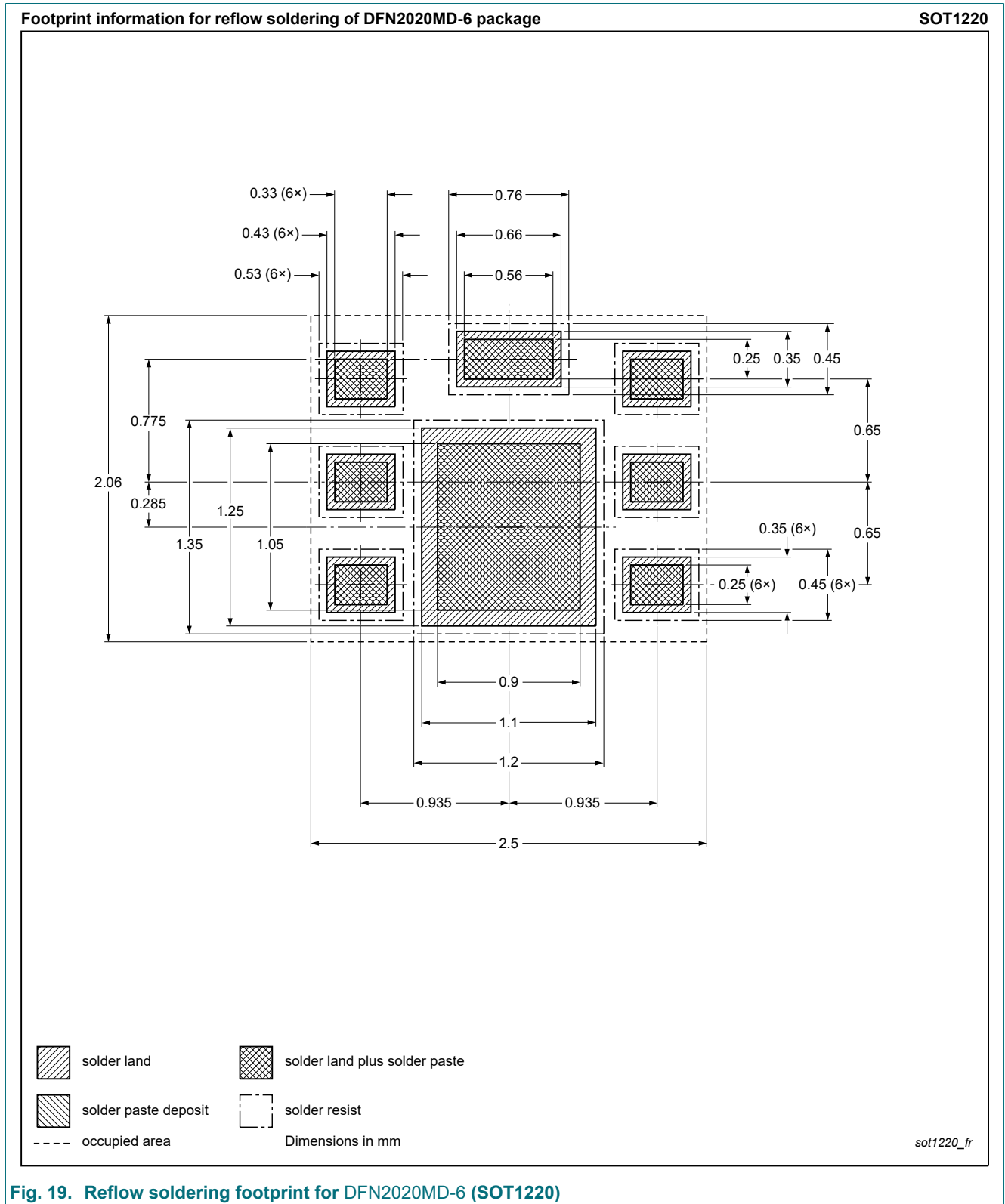


Fig. 18. Package outline DFN2020MD-6 (SOT1220)

### 13. Soldering



**Fig. 19. Reflow soldering footprint for DFN2020MD-6 (SOT1220)**

## 14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
BUK4D110-20P v.1	20200707	Product data sheet	-	-

## 15. Legal information

### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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Date of release: 7 July 2020

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